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The marking on this product doesn't contain environmental hazardous materials per directive 2011/65/EU & 2015/863/EU for RoHS compliant and per IEC 61249-2-21 for Halogen-Free compliant.



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A	NE-22159	INITIAL REVISION	2023.02.22	Ophelia OuYang

PART NO. G88MPSXX1X2XXC1HR

No. OF CIRCUIT

BOARDLOCK/CAP OPTION

CONTACT FINISH
 0: MATTE TIN 100μ"
 1: FLASH GOLD
 2: 15μ" GOLD
 3: 30μ" GOLD

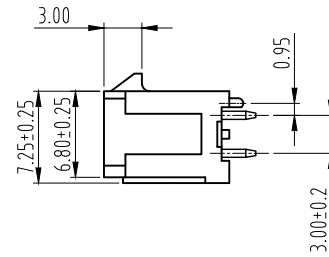
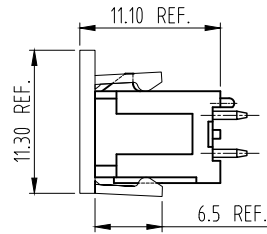
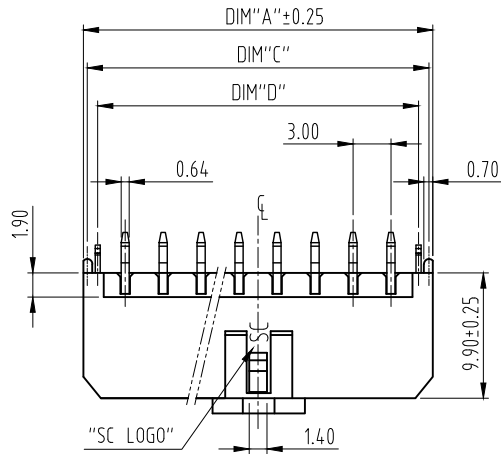
	BOARDLOCK	CAP
1	V	X
2	X	X
C	V	V
D	X	V

INSULATOR

0: LCP (BLACK), DIM"F"=2.10MM
 1: LCP (NATURAL), DIM"F"=2.10MM
 2: LCP (NATURAL), DIM"F"=2.60MM
 7: LCP (NATURAL), DIM"F"=3.20MM
 8: LCP (BLACK), DIM"F"=3.20MM

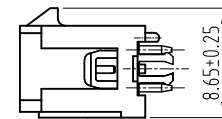
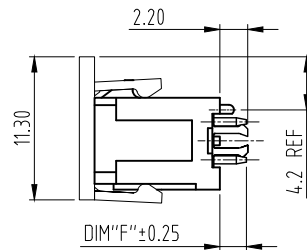
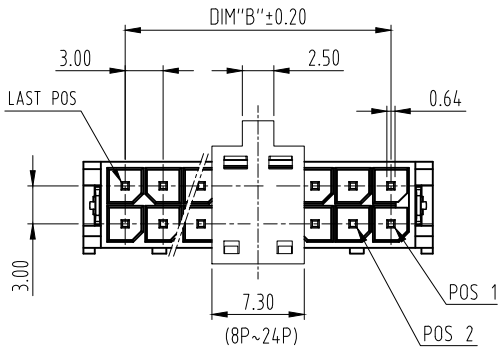
NOTE:

- MATERIAL
 HOUSING: HIGH TEMPERATURE THERMALPLASTIC, UL 94V-0, COLOR: OPTIONS
 CONTACT: HIGH PERFORMANCE COPPER ALLOY.
 BOARDLOCK: COPPER ALLOY.
- FINISH
 CONTACT:
 CONTACT AREA: SELECTIVE PLATING.
 SOLDERING AREA: MATTE TIN 100u" MIN.
 UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
 BOARDLOCK:
 MATTE TIN 100u" MIN PLATING.
 UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC & 2015/863/EU FOR RoHS AND PER IEC 61249-2-21 FOR HALOGEN FREE COMPLIANT
- PACKING MUST BE PER Amphenol PACKING SPECIFICATION
- TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.
 (G88MPSH CABLE HOUSING SERIES WITH G88MSPC CABLE TERMINAL SERIES)
- PRODUCT SPECIFICATION REFER TO : PS-7759.
- TEST SUMMARY REFER TO : TS-7759-001
- FOR 1.60MM THICKNESS PCB ONLY.



(W/O BOARDLOCK, W/CAP)

(W/O BOARDLOCK, W/O CAP)



(W/BOARDLOCK, W/CAP)

(W/BOARDLOCK, W/O CAP)

POS	DIM"A''	DIM"B''	DIM"C''	DIM"D''
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

TOLERANCE	DRAWN	APPROVALS	DATE
X.	DESIGNED	Ophelia OuYang	2023.02.22
X.X ±0.30	CHECKED	Chenny Yeh	2023-03-29
X.XX ±0.20	APPROVED	Hank Hsu	2023-03-29
X.XXX ±0.10	DWG TYPE	CUST DWG	PROJECT CODE T645
ANGULAR ±2°	UNLESS OTHERWISE SPECIFIED		

TITLE			
G88MPS SERIES MICRO POWER SUPER, WAFER 3.00 MM PITCH STRAIGHT DIP			
UNIT	mm	SIZE	A3
SCALE	NA	SHEET	1 OF 3

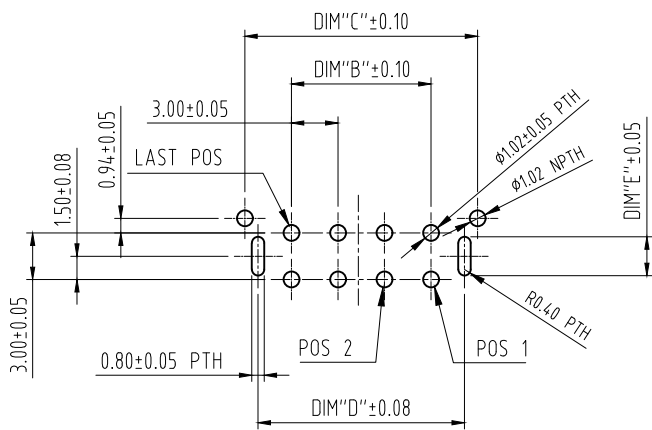
Amphenol®	
Amphenol Corporation Amphenol Taiwan Corporation	
PART No.	G88MPSXX1X2XXC1HR
DWG No.	G88MPSXX1X2XXC1HR
REV.	A

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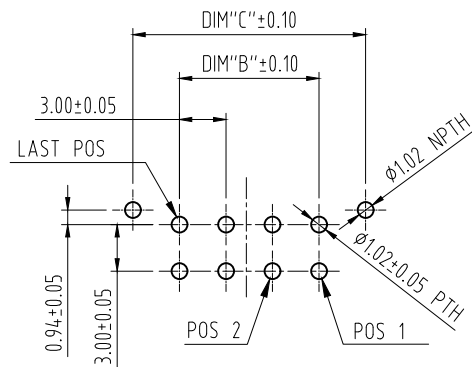
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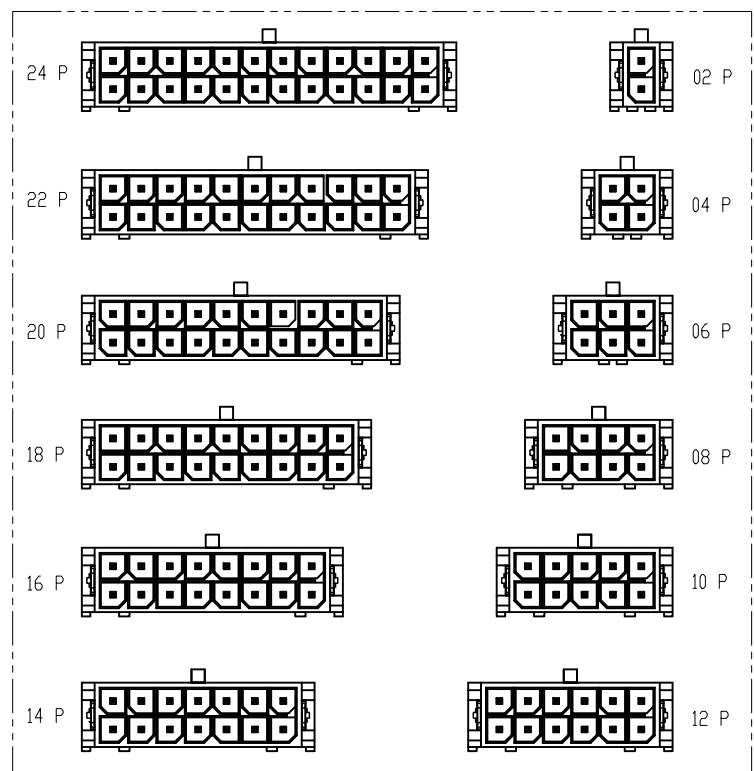
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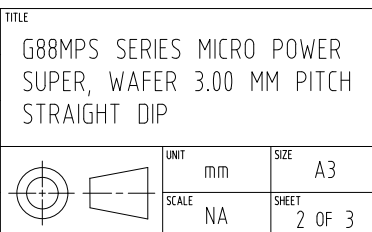
DIM"E": 2.50 FOR NON-ZERO INSERTION FORCE
 DIM"E": 3.00 FOR ZERO INSERTION FORCE



02~24P (W/O BOARDLOCK)
 RECOMMENDED PCB LAYOUT(T=1.60mm)



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X.XX ±0.20	CHECKED	Chenny Yeh	2023-03-29	
X.XXX ±0.10	APPROVED	Hank Hsu	2023-03-29	
ANGULAR ±2°	DWG TYPE	CUST DWG	PROJECT CODE T645	



UNIT mm		SIZE A3	PART No. G88MPSXX1X2XXC1HR
SCALE NA	SHEET 2 OF 3	DWG No. G88MPSXX1X2XXC1HR	
UNLESS OTHERWISE SPECIFIED			REV. A

Amphenol®

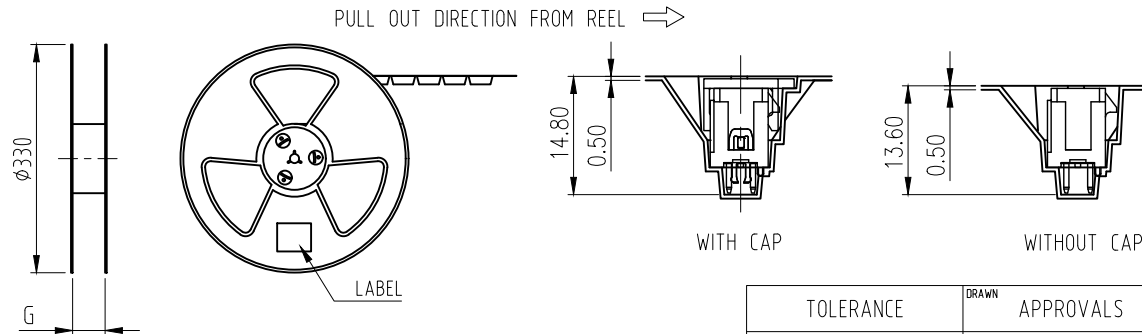
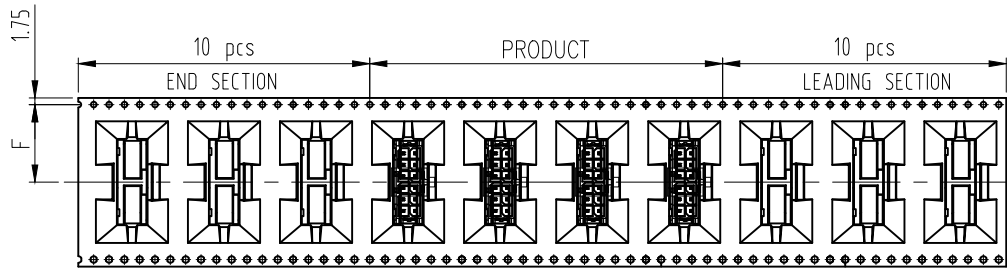
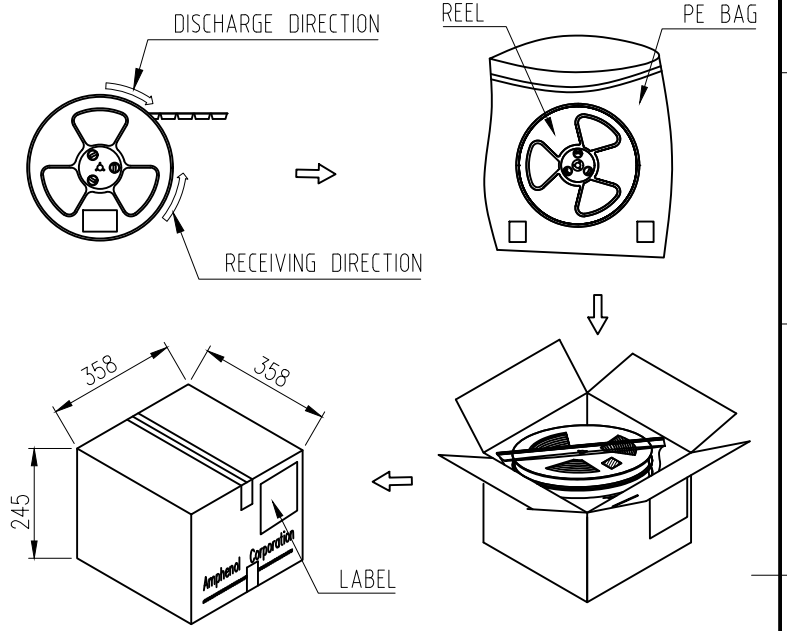
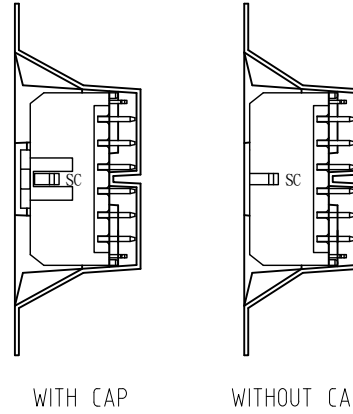
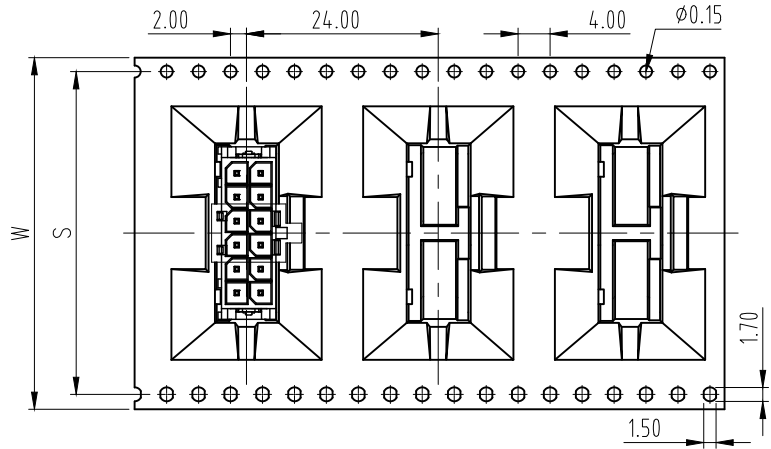
Amphenol Corporation
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POS	W	S	F	G	PCS/REEL	PCS/CARTON
2x1	32.00	28.40	14.20	38.00	150	900
2x2						450
2x3						
2x4	44.00	40.40	20.20	50.00		
2x5						
2x6						
2x7						
2x8	56.00	52.40	26.20	62.00		
2x9						
2x10						
2x11	72.00	68.40	34.20	78.00		
2x12						

TOLERANCE	DRAWN	APPROVALS	DATE	TITLE	Amphenol®			
X. ±0.30	DESIGNED	Ophelia OuYang	2023.02.22	G88MPS SERIES MICRO POWER SUPER, WAFER 3.00 MM PITCH STRAIGHT DIP	Amphenol Corporation Amphenol Taiwan Corporation			
X.X ±0.20	CHECKED	Chenny Yeh	2023-03-29					
X.XXX ±0.10	APPROVED	Hank Hsu	2023-03-29					
ANGULAR ±2°	DWG TYPE	CUST DWG	PROJECT CODE T645	UNIT mm	SIZE A3	PART No.	G88MPSXX1X2XXC1HR	
UNLESS OTHERWISE SPECIFIED				SCALE NA	SHEET 3 OF 3	DWG No.	G88MPSXX1X2XXC1HR	
						REV.	A	

单击下面可查看定价，库存，交付和生命周期等信息

[>>Amphenol\(安费诺\)](#)